Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1001-01** DATE: **Apr 2, 2010**

Product Affected: TSI148-133CL
TSI148-133IL
(Package Type: PBGA)

Date Effective: **Jul 2, 2010**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ■ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ☐ Other

Laser Top Mark and IDT logo
(Previously Tundra logo)

Contact: Mary Vesey
Title: Director, Product Assurance
Phone #: (408) 284-4565
Fax #: (408) 284-1450
E-mail: Mary.Vesey@idt.com

Attachment: ■ Yes ☐ No

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ■ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ■ Other - Top Mark

This notification is to inform our customers that IDT is converting to a new mold compound, Sumitomo G770J and die attach epoxy, Ablebond 2100A as a result of the existing mold compound being obsoleted by the vendor.

In addition, product top mark will be changed from Ink mark to Laser mark and the change to the mark format from Tundra to IDT, as annouced in a previous PCN TS-0906-01 will be coincident with this change.

Attachment I: Details of change.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 90 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

ATTACHMENT I - PCN # : A1001-01

PCN Type: Assembly Material & Product Top Mark

Data Sheet Change: None

Details Of Change: This notification is to inform our customers that IDT is converting to a new mold compound, Sumitomo G770J and die attach epoxy, Ablebond 2100A as a result of the existing mold compound being obsoleted by the vendor.

In addition, product top mark will be changed from Ink mark to Laser mark and the change to the mark format from Tundra to IDT, as annouced in a previous PCN TS-0906-01 will be coincident with this change.

There is no change in the moisture sensitivity level (MSL).

Description	Changes	
	From	To
Mold Compound	SMT-B1-FX	Sumitomo G770J
Die Attach Epoxy	Ablebond 8355F	Ablebond 2100A
Product Top Mark	Ink Mark	Laser Mark

Qualification Test Plan and Results:

Test Vehicle: 40mm EPBGA

Test Description	Test Results (SS/Rej)
* Temperature Cycling (-65/150 °C, 500 cycles)	75/0
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 96 Hrs)	45/0
High Temperature Stabilization Bake (150 °C, 1000 hours)	45/0
Moisture Sensitivity Classification, Level 3 @ 260 °C	165/0

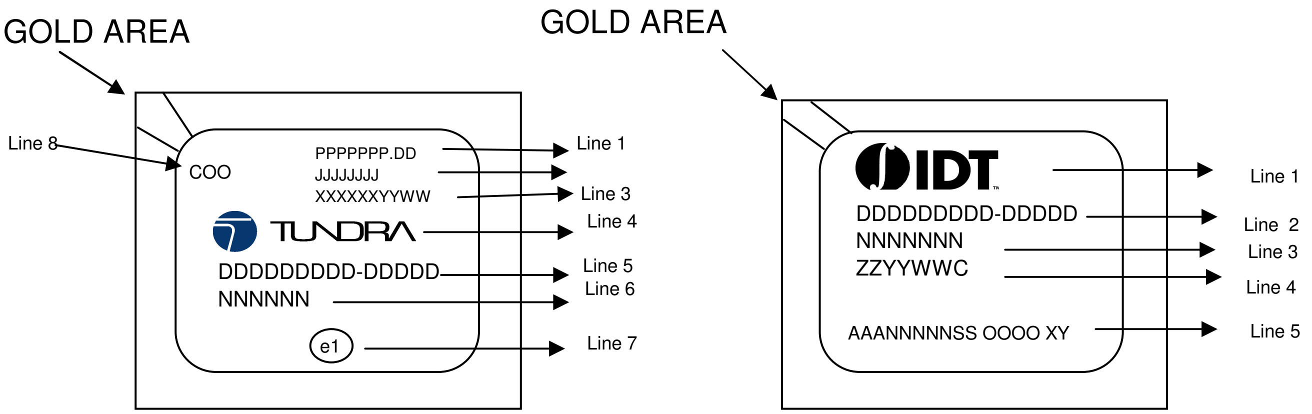
Note: * Test require moisture pre-conditioning sequence per JESD22-A113.

ATTACHMENT I - PCN # : A1001-01

Top Mark Date and lot code change by Package Type

Package Type: PBGA and HSBGA

FROM **TO**



Line 1 - PPPPPPP- wafer part no
    DD- Wafer ID
Line 2 - JJJJJJJ - Wafer lot no
Line 3 - XXXXXXYYWW - assembly lot no and date code
Line 4 - Tundra Logo
Line 5 - DDDDDDDDD-DDDDD- part number
Line 6 - Product Name
Line 7 - Lead Free symbol
Line 8 - Some devices may have COO

Line 1 - IDT LOGO
Line 2- DDDDDDDDD-DDDDD - Part Number
Line 3 - Product Name
Line 4 - date code where
    ZZ is device stepping
    YY- Year
    WW - Workweek
    C - mark location code
Line 5 - AAANNNNNSS - assembly lot no
    OOOO - Country of origin
    xy- seal code